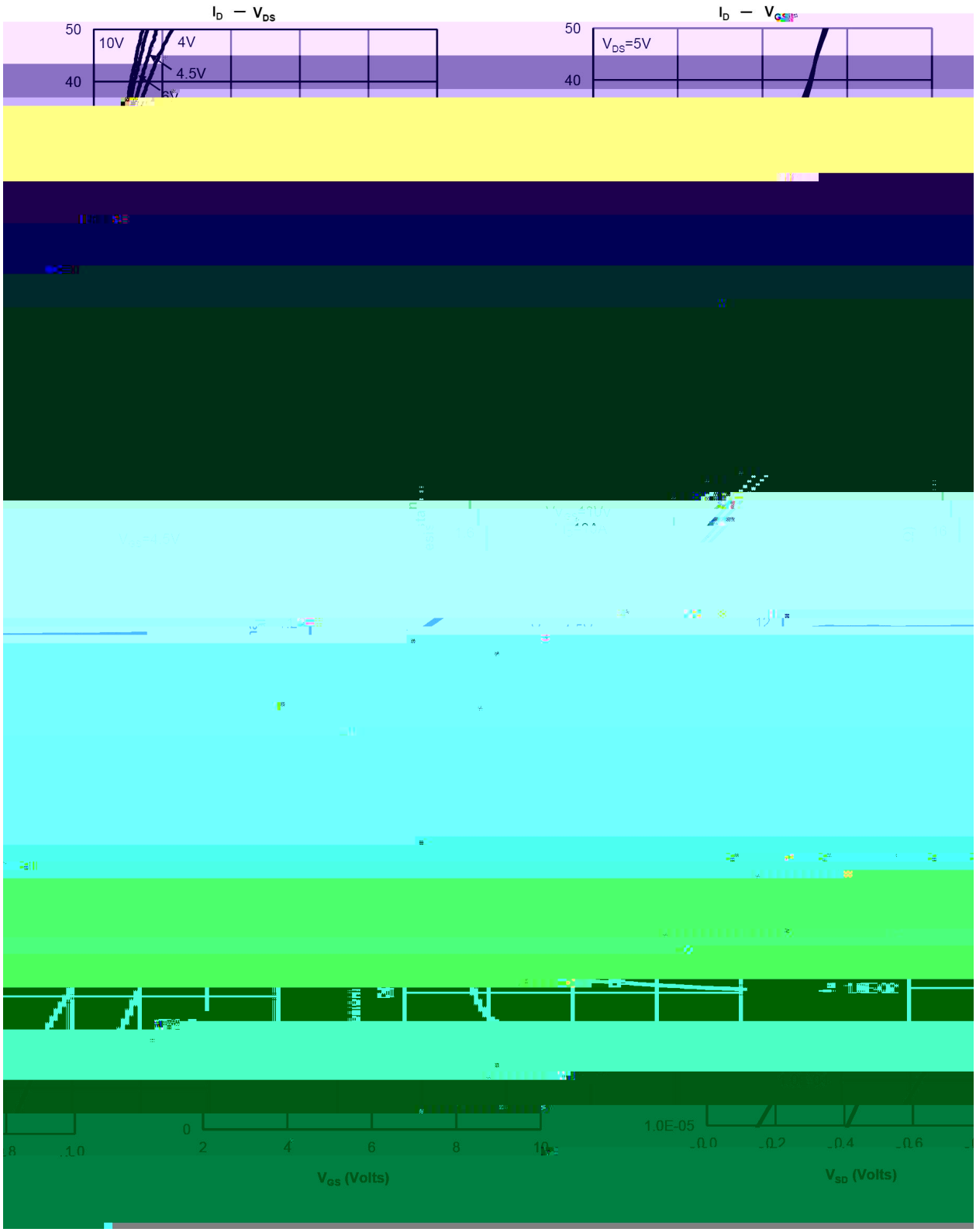
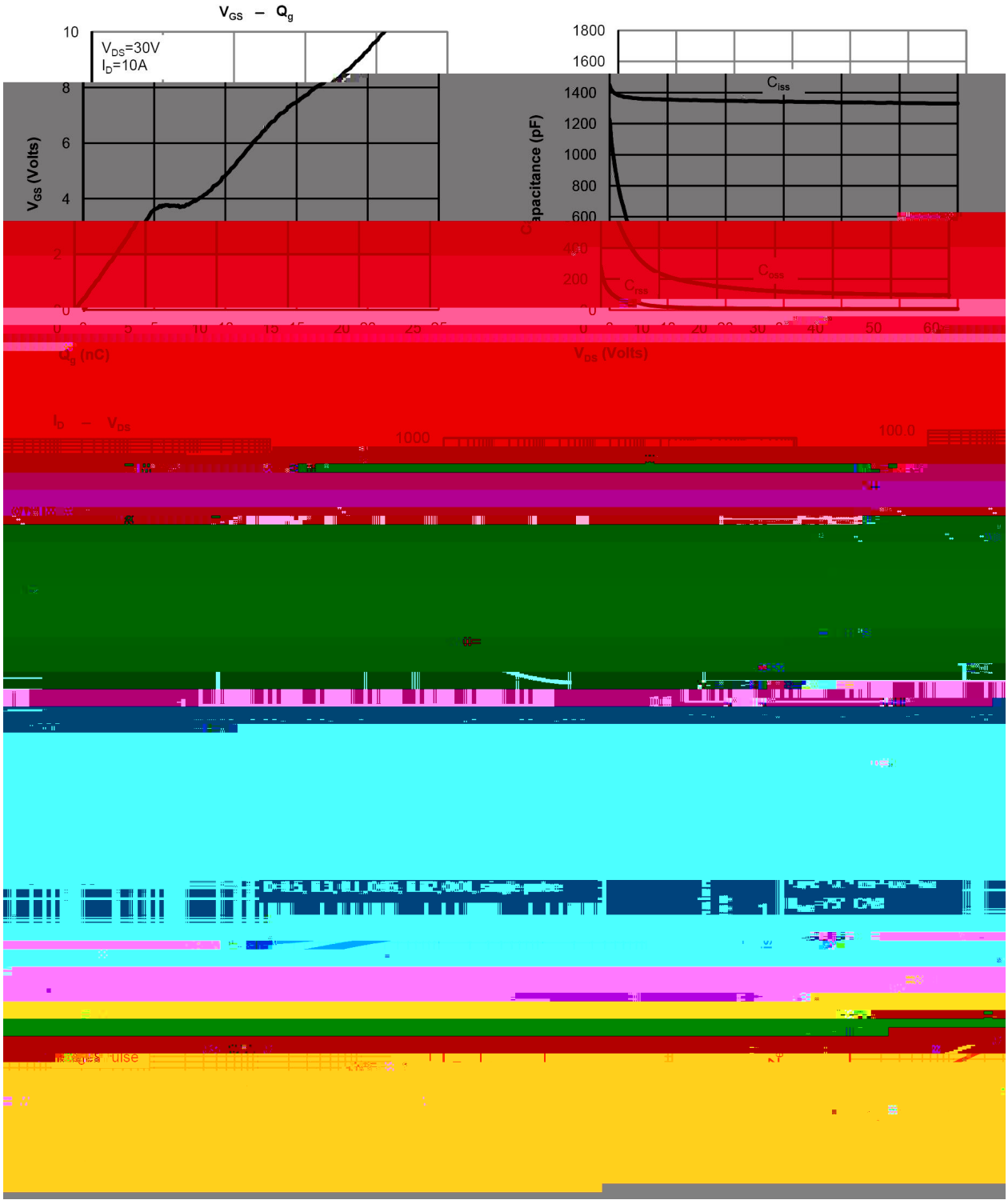
v ̈Ω Parameter	ϒ N Symbol	̈Ω Ö Rating	D Ɥ Unit

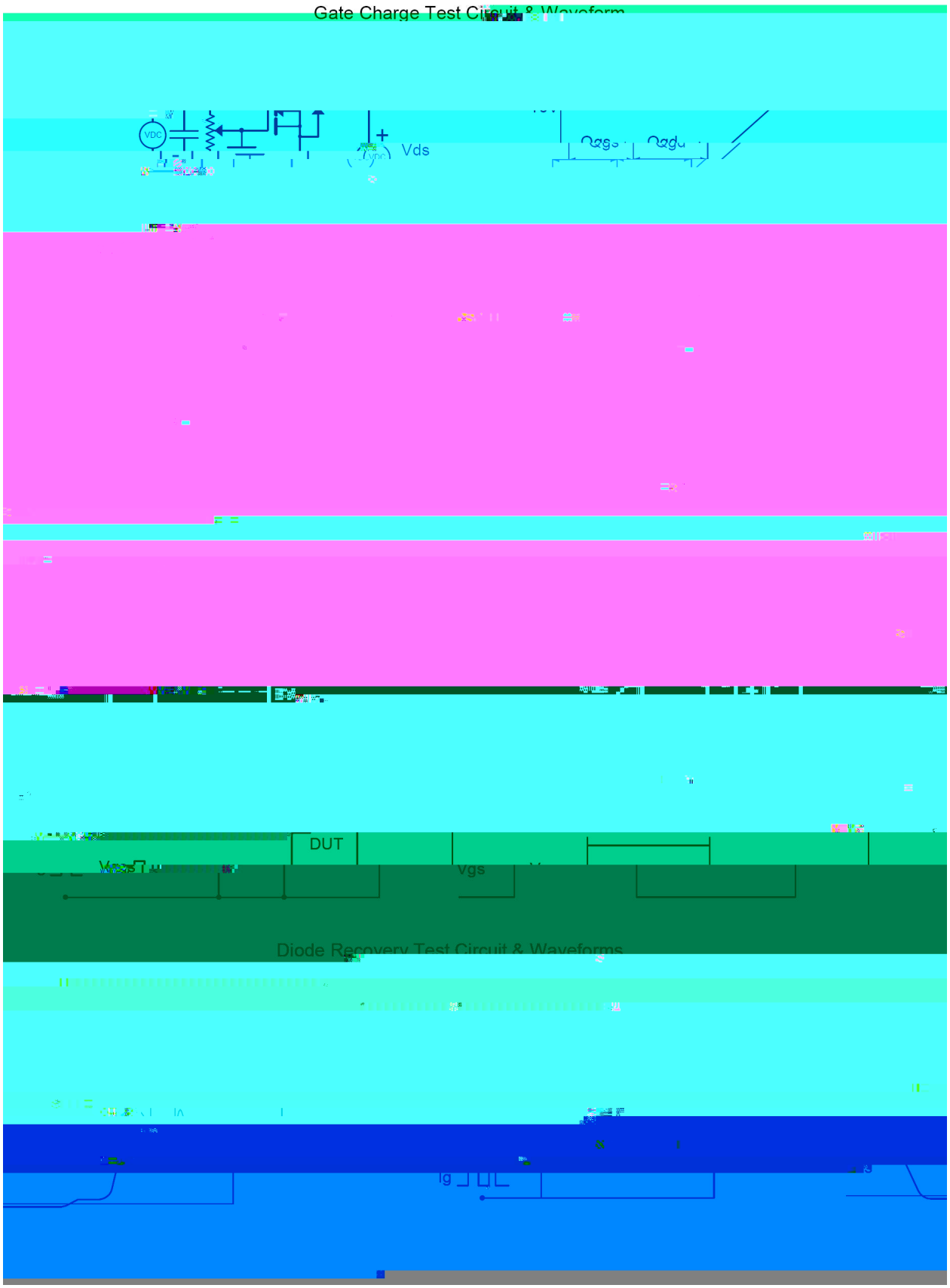
/ Electrical Characteristic Curve



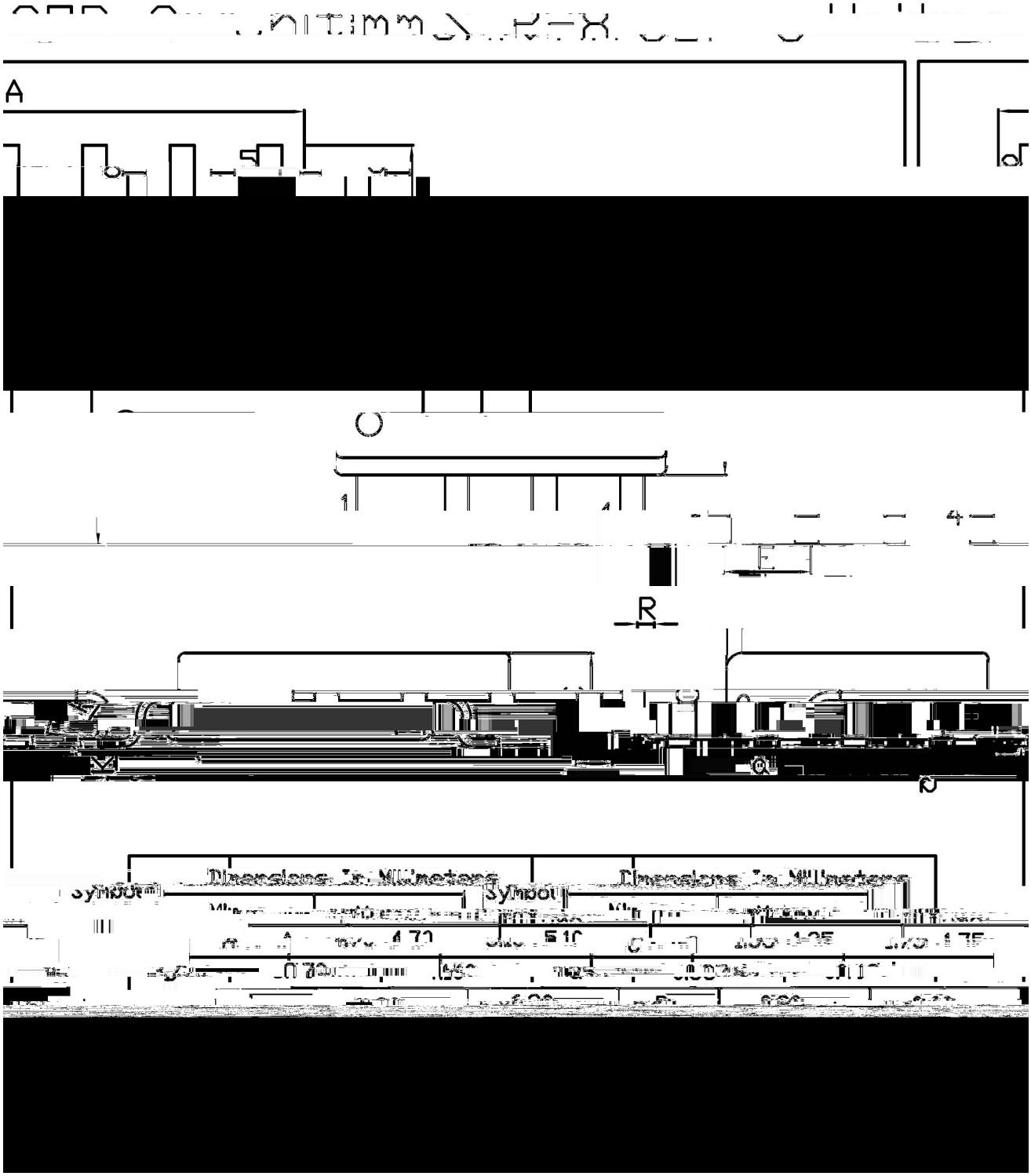
/ Electrical Characteristic Curve



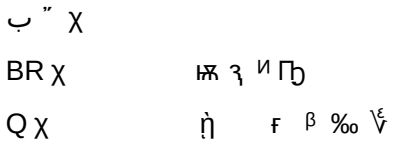
/ Test Circuit & Waveform



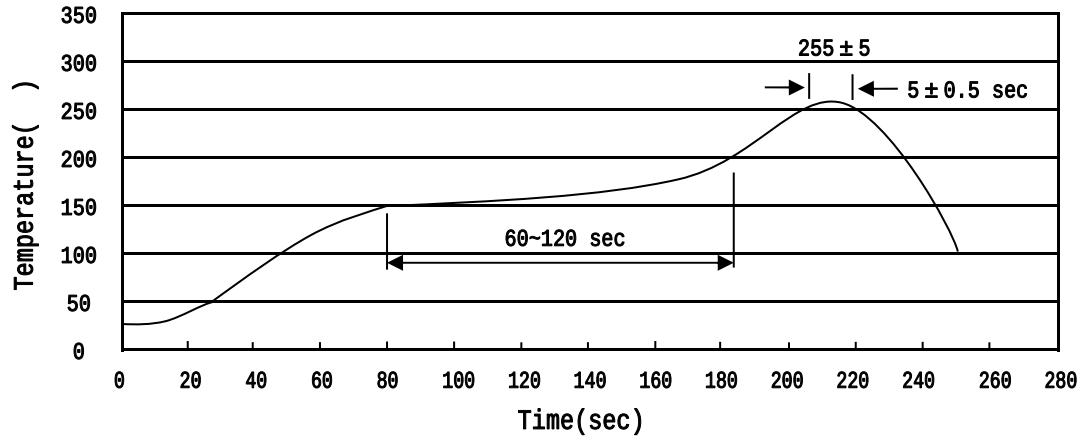
/ Package Dimensions



/ Marking Instructions



( ) / Temperature Profile for IR Reflow Soldering(Pb-Free)



ب ˝ χ

1 Ĺ ♬ □ ỷ 150 Ḱ 200 ɬ ı `H ڑ 60 Ḱ 120sec;

2 Š Ë □ ỷ 255 ° 5 ɬ ı `H ڑ 'Y ʌ ʬ 5 ° 0.5sec;

3 ì ˙ ٧ ˛ ɔ ♨ ỷ ʬ 2 Ḱ 10 ɬ /sec.

Note:

1.Preheating:150~200 ɬ , Time:60~120sec.

2.Peak Temp.:255 ° 5 ɬ , Duration:5 ° 0.5sec.

3. Cooling Speed: 2~10 ɬ /sec.

/ Resistance to Soldering Heat Test Conditions

□ ỷ χ 260 ° 5 ɬ `H ڑ χ 10 ° 1 sec. Temp.:260±5 ɬ Time:10±1 sec

/ Packaging SPEC.

ɔ ` ٧ Ł / REEL

Package Type	Units					Dimension		(unit mm³)
	Units/Reel /	Reels/Inner Box /	Units/Inner Box /	Inner Boxes/Outer Box /	Units/Outer Box /	Reel	Inner Box	Outer Box
SOP/ESOP-8	4,000	2	8,000	6	48,000	13 ×12	360×360×50	380×335×366

/ Notices